



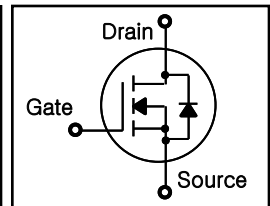
# PFU65R540G / PFD65R540G

## N-Channel Super Junction MOSFET

### FEATURES

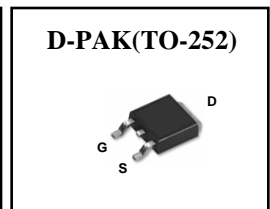
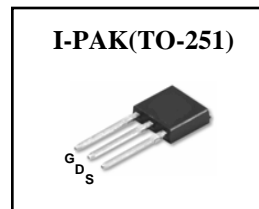
- New technology for high voltage device
- Low  $R_{DS(on)}$  low conduction losses
- Small package
- Ultra low gate charge cause lower driving requirement
- 100% avalanche tested
- Halogen Free

**$BV_{DSS} = 650\text{ V}$**   
 **$R_{DS(on)} = 0.48\ \Omega$**   
 **$I_D = 8.0\text{ A}$**



### APPLICATION

- Power Factor Correction(PFC)
- Switch mode power supply (SMPS)
- Uninterruptible Power Supply (UPS)



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	650	V
$I_D$	Drain Current – Continuous ( $T_c = 25^\circ\text{C}$ )	8.0	A
	Drain Current – Continuous ( $T_c = 100^\circ\text{C}$ )	5.2	A
$I_{DM(pulse)}$	Drain Current – Pulsed * Note 1	24	A
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0\text{V}$ )	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy * Note 2	185	mJ
$I_{AR}$	Avalanche Current * Note 1	4.0	A
$E_{AR}$	Repetitive Avalanche Energy * Note 1	0.4	mJ
dv/dt	Drain Source Voltage Slope, $V_{DS} \leq 480\text{V}$	50	V/ns
	Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}$	15	V/ns
$P_D$	Maximum Power Dissipation ( $T_c = 25^\circ\text{C}$ )	80	W
	Derate above $25^\circ\text{C}$	0.64	W/ $^\circ\text{C}$
$T_I, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$

\* Limited by maximum junction temperature

### Thermal Resistance Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Junction-to-Case (Maximum)	1.56	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient (Maximum)	62	

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**Electrical Characteristics**  $T_A=25\text{ }^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.5	3.0	3.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 4.0\text{ A}$	--	480	540	m.ohm
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	650	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	$\mu\text{A}$
		$V_{DS} = 650\text{ V}, T_C = 125\text{ }^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
<b>Dynamic Characteristics</b>						
$g_{FS}$	Forward Transconductance	$V_{DS} = 20\text{ V}, I_D = 4.0\text{ A}$	--	5.5	--	S
$R_G$	Intrinsic Gate Resistance	$f = 1.0\text{ MHz}$ , open drain	--	2	--	ohm
$C_{iss}$	Input Capacitance	$V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	680	--	pF
$C_{oss}$	Output Capacitance		--	58	--	pF
$C_{riss}$	Reverse Transfer Capacitance		--	4	--	pF
$Q_g$	Total Gate Charge	$V_{DS} = 480\text{ V}, I_D = 8.0\text{ A},$ $V_{GS} = 10\text{ V}$	--	14.5	22	nC
$Q_{gs}$	Gate-Source Charge		--	2.8	--	nC
$Q_{gd}$	Gate-Drain Charge		--	5.5	--	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Time	$V_{DS} = 380\text{ V}, I_D = 4.0\text{ A},$ $R_G = 12\text{ }\Omega, V_{GS} = 10\text{ V}$	--	5.5	--	ns
$t_r$	Turn-On Rise Time		--	3.5	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	55	75	ns
$t_f$	Turn-Off Fall Time		--	6.5	10	ns
<b>Source-Drain Diode Maximum Ratings and Characteristics</b>						
$I_S$	Continuous Source-Drain Diode Forward Current		--	--	8.0	A
$I_{SM}$	Pulsed Source-Drain Diode Forward Current		--	--	23.4	
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 8.0\text{ A}, V_{GS} = 0\text{ V}$	--	0.9	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_S = 8.0\text{ A}$	--	220	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt = 100\text{ A}/\mu\text{s}$	--	2.2	--	$\mu\text{C}$

**Notes ;**

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $V_{DD}=50\text{ V}, R_G=25\text{ }\Omega$ , Starting  $T_J=25\text{ }^\circ\text{C}$

## Typical Characteristics

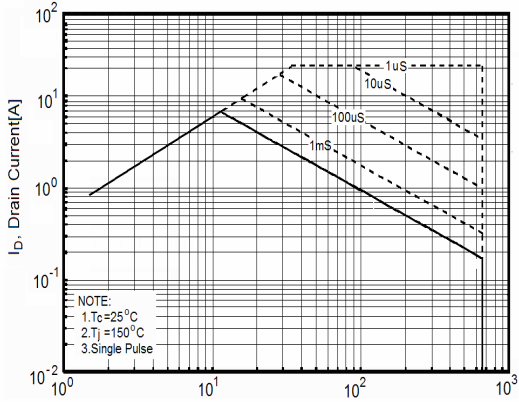


Figure 1. Safe Operating Area

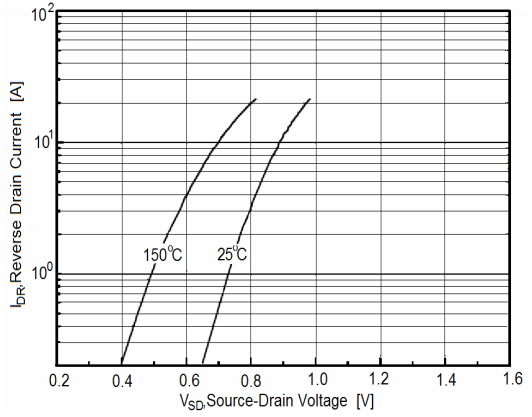


Figure 2. Source-Drain Diode Forward Voltage

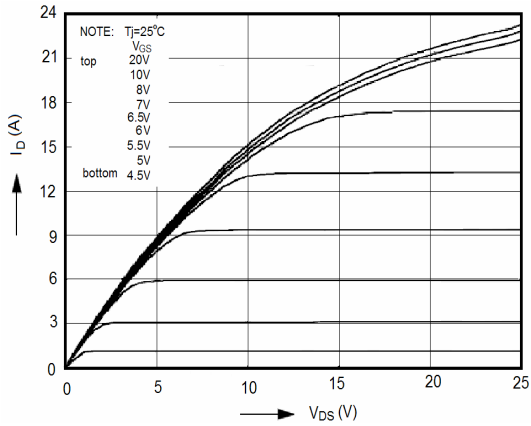


Figure 3. Output Characteristics

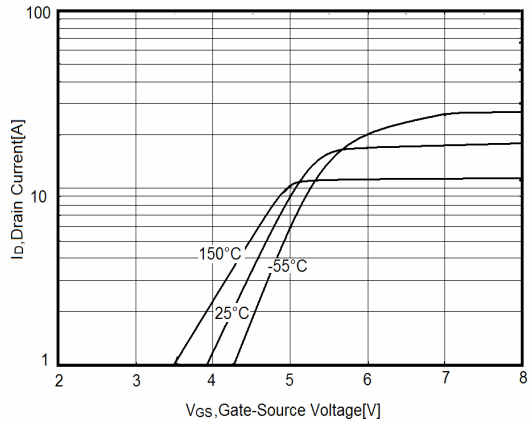


Figure 4. Transfer Characteristics

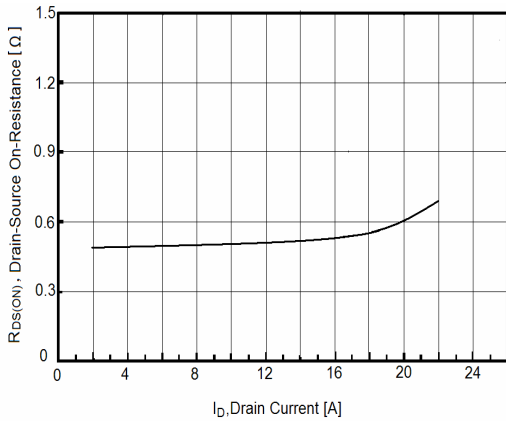


Figure 5. Static Drain-Source On Resistance

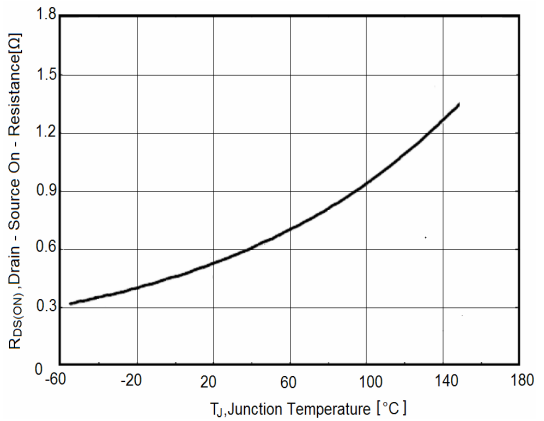


Figure 6.  $R_{DS(on)}$  vs. Junction Temperature

Typical Characteristics (continued)

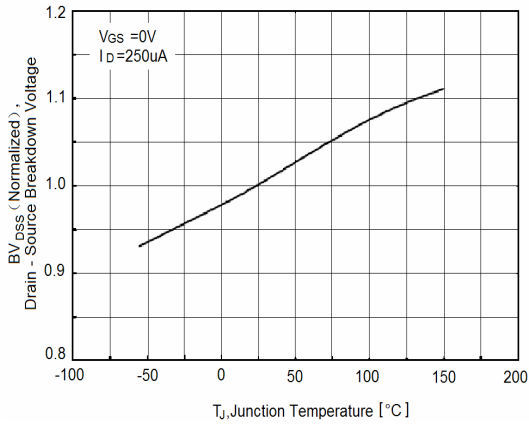


Figure 7. BVDSS vs. Junction Temperature

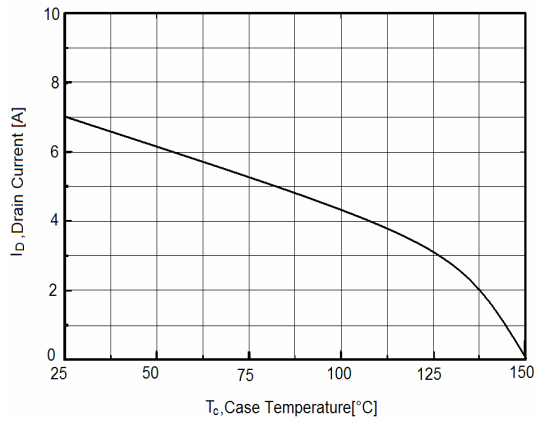


Figure 8. Maximum ID vs. Junction Temperature

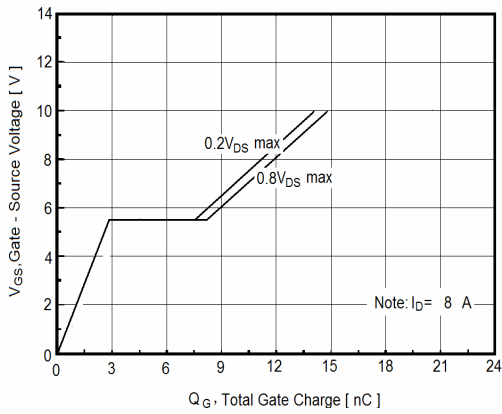


Figure 9. Gate Charge Waveforms

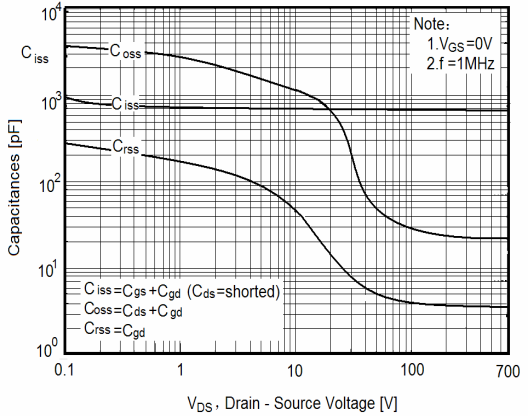


Figure 10. Capacitance

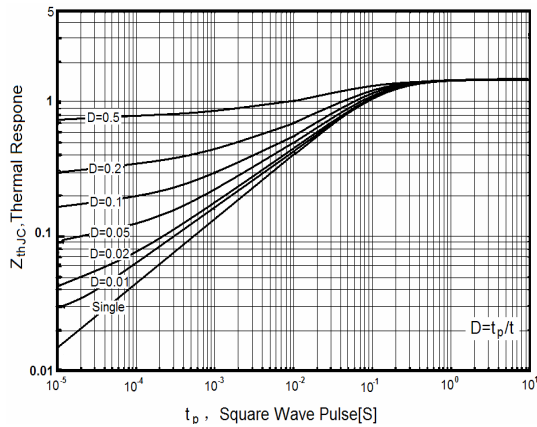
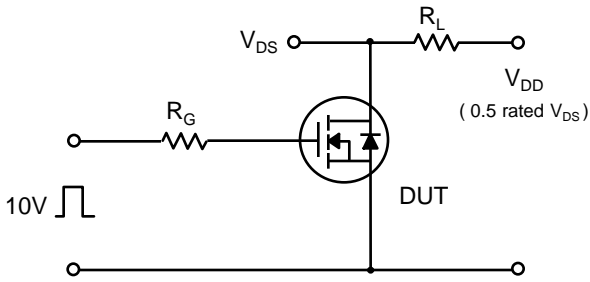
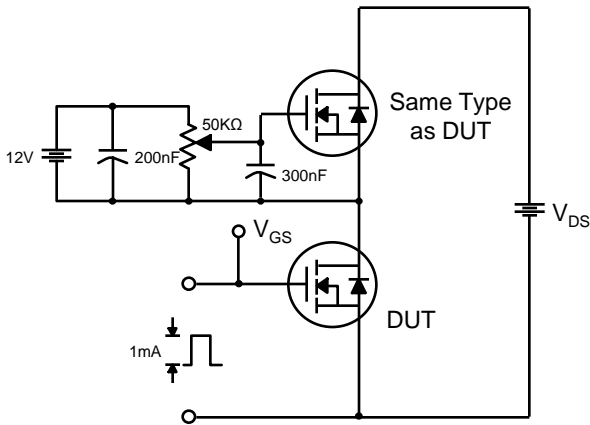


Figure 11. Transient Thermal Response Curve

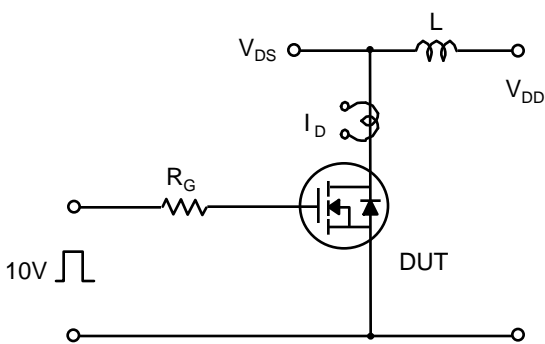
Characteristics Test Circuit & Waveform



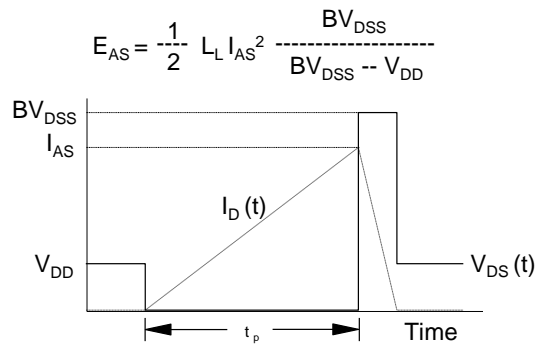
Switching Time Test Circuit & Waveforms



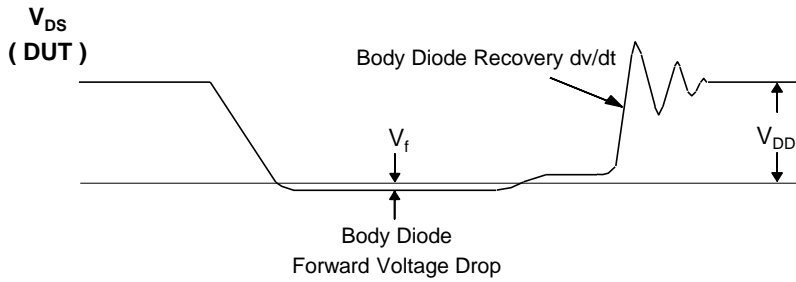
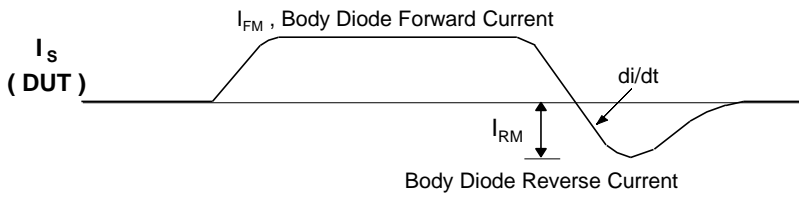
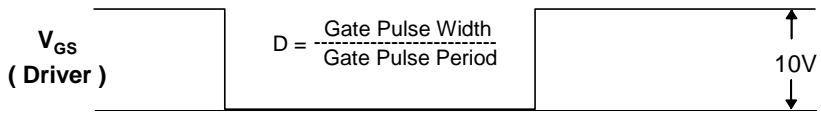
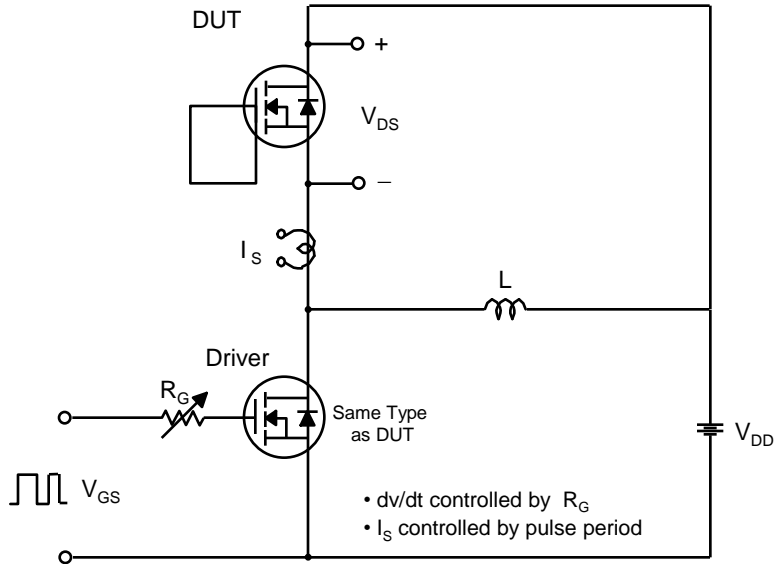
Gate Charge Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveforms



Characteristics Test Circuit & Waveform (continued)



Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms